

DMT6009LK3-13 Datasheet

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DiGi Electronics Part Number DMT6009LK3-13-DG

Manufacturer Diodes Incorporated

Manufacturer Product Number DMT6009LK3-13

Description MOSFET N-CH 60V 13.3A/57A TO252

Detailed Description N-Channel 60 V 13.3A (Ta), 57A (Tc) 2.6W (Ta) Surfa

ce Mount TO-252-3



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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
DMT6009LK3-13	Diodes Incorporated
Series:	Product Status:
	Active
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
60 V	13.3A (Ta), 57A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
4.5V, 10V	10mOhm @ 13.5A, 10V
Vgs(th) (Max) @ Id:	Gate Charge (Qg) (Max) @ Vgs:
2V @ 250μA	33.5 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±16V	1925 pF @ 30 V
FET Feature:	Power Dissipation (Max):
	2.6W (Ta)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
TO-252-3	TO-252-3, DPAK (2 Leads + Tab), SC-63
Base Product Number:	
DMT6009	

Environmental & Export classification

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	





60V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
	10mΩ @ V _{GS} = 10V	57A
60V	12.8mΩ @ V _{GS} = 4.5V	51A

Features

- Low R_{DS(ON)} Ensures On State Losses Are Minimized
- Excellent Q_{gd x} R_{DS(ON)} Product (FOM)
- Advanced Technology for DC/DC Converters
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high- efficiency power management applications.

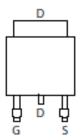
- Power Management Functions
- DC-DC Converters
- Backlighting

Mechanical Data

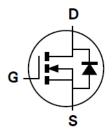
- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe;
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.33 grams (Approximate)



Top View



Pin Out Top View



Equivalent Circuit

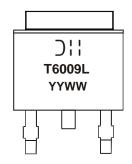
Ordering Information (Note 4)

Part Number	Case	Packaging
DMT6009LK3-13	TO252	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Dili=Manufacturer's Marking
T6009L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 15 = 2015)
WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	60	V
Gate-Source Voltage		V_{GSS}	±16	V
Continuous Drain Current (Note 5) V _{GS} = 10V	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	13.3 10.6	Α
Continuous Drain Current (Note 6) V _{GS} = 10V	$T_C = +25$ °C $T_C = +70$ °C	I _D	57 46	Α
Maximum Continuous Body Diode Forward Current (Note 6)		Is	80	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	90	Α
Avalanche Current, L=0.1mH		I _{AS}	20.3	А
Avalanche Energy, L=0.1mH		E _{AS}	20.6	mJ

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	2.6	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	47	°C/W
Total Power Dissipation (Note 6)	P_{D}	50	W
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	2.5	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)				•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	60	-	-	V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1	μA	$V_{DS} = 48V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.7	1.4	2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	D	-	8.3	10	mΩ	$V_{GS} = 10V, I_D = 13.5A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	-	9.6	12.8	mΩ	$V_{GS} = 4.5V, I_D = 11.5A$	
Diode Forward Voltage	V _{SD}	-	0.9	1.2	V	V _{GS} = 0V, I _S = 20A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	-	1,925	-		.,	
Output Capacitance	Coss	-	438	-	pF	$V_{DS} = 30V$, $V_{GS} = 0V$, $f = 1MHz$	
Reverse Transfer Capacitance	Crss	-	41	-			
Gate Resistance	Rg	-	1.7	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	-	15.6	-			
Total Gate Charge (V _{GS} = 10V)	Qg	-	33.5	-	nC	$V_{DS} = 30V, I_D = 13.5A$	
Gate-Source Charge	Q _{qs}	-	4.7	-	nc nc		
Gate-Drain Charge	Q_{gd}	-	5.3	-			
Turn-On Delay Time	t _{D(ON)}	-	4.5	-		$V_{DD} = 30V, V_{GS} = 10V,$ $R_G = 6\Omega, I_D = 13.5A$	
Turn-On Rise Time	t _R	-	8.6	-			
Turn-Off Delay Time	t _{D(OFF)}	-	35.9	-	ns		
Turn-Off Fall Time	t _F	-	15.7	-			
Body Diode Reverse Recovery Time	t _{RR}	-	18.2	-	ns	1. 40.54 47/4 4004/	
Body Diode Reverse Recovery Charge	Q _{RR}	-	33.1	-	nC	$I_F = 13.5A$, di/dt = 400A/ μ s	

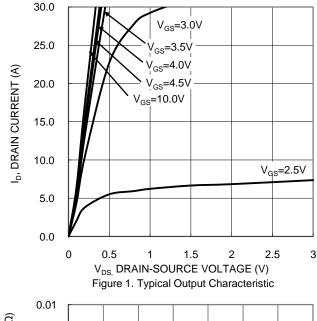
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.

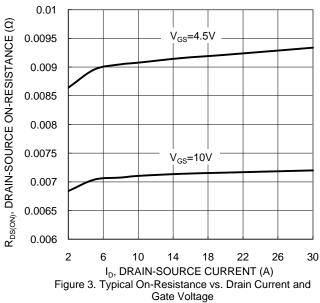
^{6.} Device mounted on infinite heat sink and measured by thermal couple attached on bottom heat sink of package.

^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.







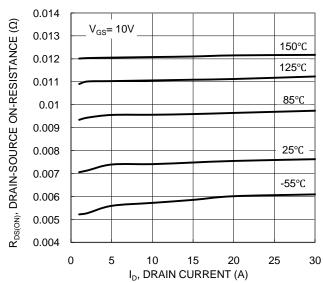
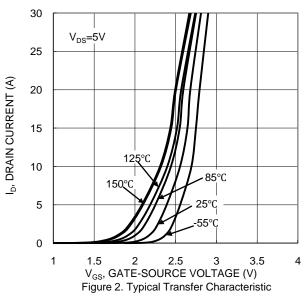
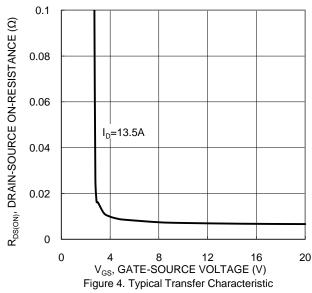


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





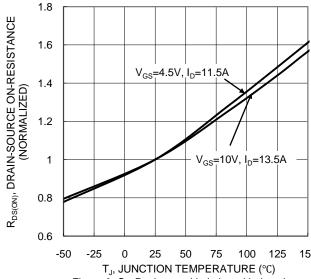
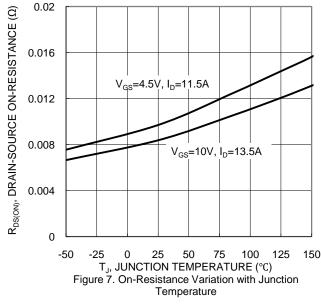
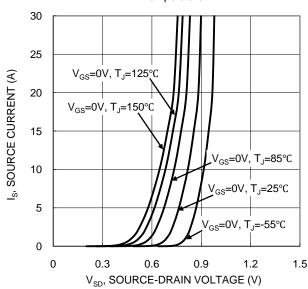
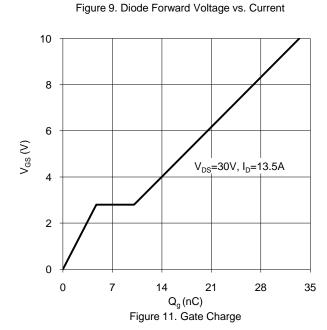


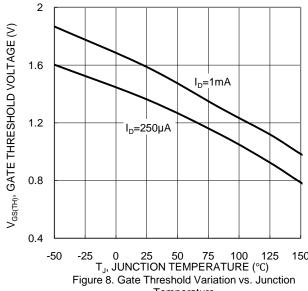
Figure 6. On-Resistance Variation with Junction Temperature

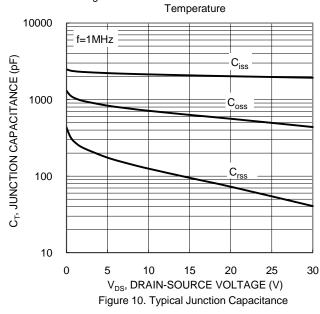


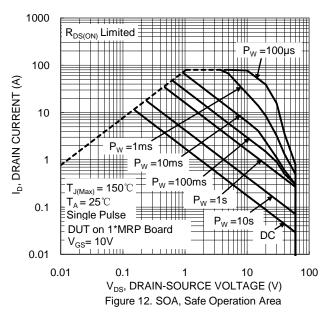














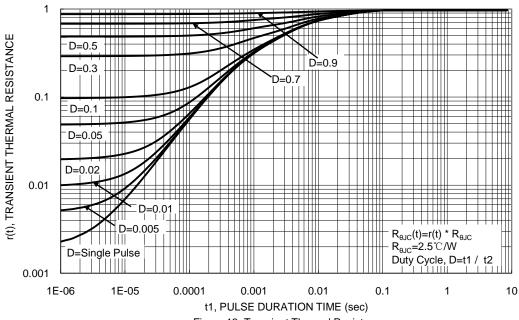
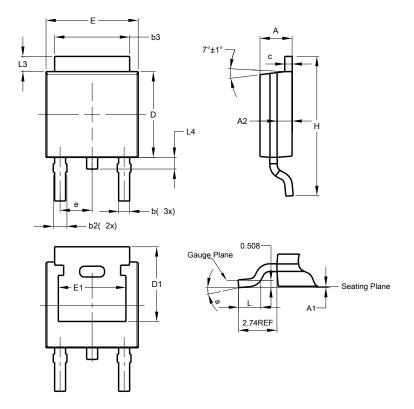


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

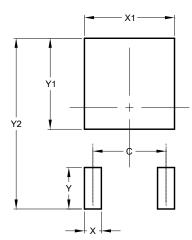


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	•	-		
H	9.40	10.41	9.91		
Г	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	4.572
Х	1.060
X1	5.632
Υ	2.600
Y1	5.700
Y2	10.700

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